PK172 (v1.6) April 26, 2013

100% Material Declaration Data Sheet for VQ64 Package

Average Weight: 0.2678 g

Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
Silicon Die					**0.005730**	**2.140**
	Silicon (Si)	7440-21-3	100.00		0.005730	
Die Attach					**0.001256**	**0.469**
	Silver (Ag)	7440-22-4	72.00		0.000904	
	Epoxy Resin	Trade Secret	15.00		0.000189	
	Anhydride	Trade Secret	10.00		0.000126	
	1,4-Butanedioldiglycidyl ether	2425-79-8	3.00		0.000038	
Mold Compound					**0.177850**	**66.410**
	Epoxy Resin	Trade secret	7.00		0.012450	
	Phenol Resin	Trade secret	5.00		0.008893	
	Carbon Black	1333-86-4	0.30		0.000534	
	Fused Silica	60676-86-0	87.70		0.155974	
Leadframe					**0.077400**	**28.902**
	Copper (Cu)	7440-50-8	98.28		0.076069	
	Chromium (Cr)	7440-47-3	0.25		0.000194	
	Tin (Sn)	7440-31-5	0.25		0.000194	
	Zinc (Zn)	7440-66-6	0.22		0.000170	
	Silver (Ag)	7440-22-4	1.00		0.000774	
Solder Plating					**0.003780**	**1.411**
	Tin (Sn)	7440-31-5	85.00		0.003213	
	Lead (Pb)	7439-92-1	15.00		0.000567	
Gold Wire					**0.001790**	**0.668**
	Gold (Au)	7440-57-5	99.00		0.001772	
	Palladium	7440-05-3	1.00		0.000018	

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Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
03/20/06	1.0	Initial Xilinx release.
07/05/06	1.1	100% Material Declaration
08/31/06	1.2	Corrected leadframe component weight
10/03/06	1.3	Updated component descriptions
11/18/11	1.4	Updated component weights and descriptions
08/24/12	1.5	Updated CAS # in Die Attach
04/26/13	1.6	Updated CAS Description in Die Attach

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